



Welcome to **E-XFL.COM**

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	86
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega1280-16aur

1. Pin Configurations

Figure 1-1. TQFP-pinout ATmega640/1280/2560

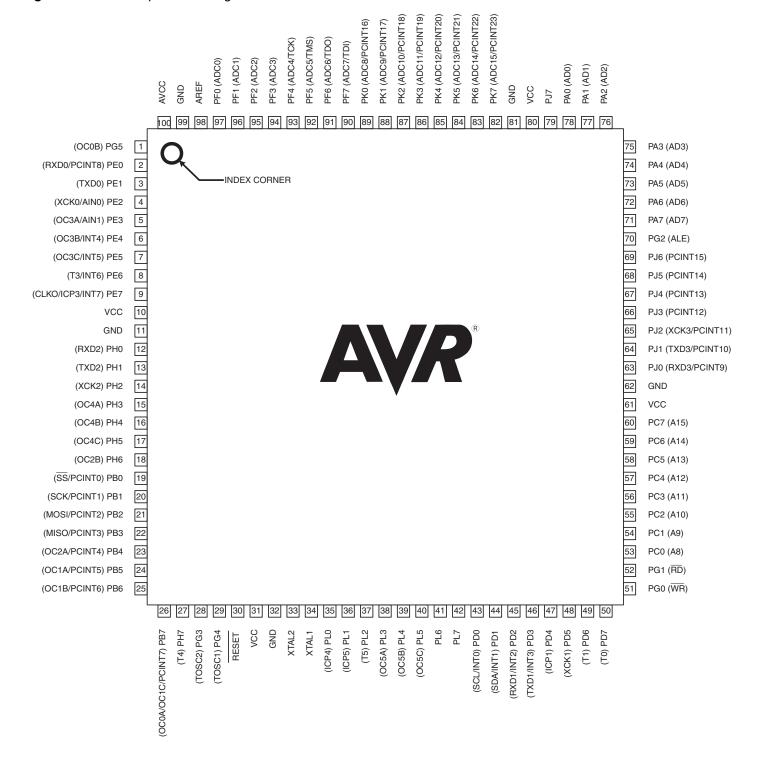




Figure 1-2. CBGA-pinout ATmega640/1280/2560

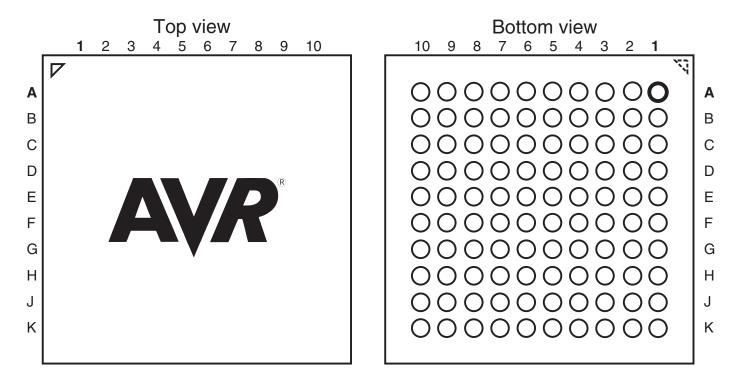


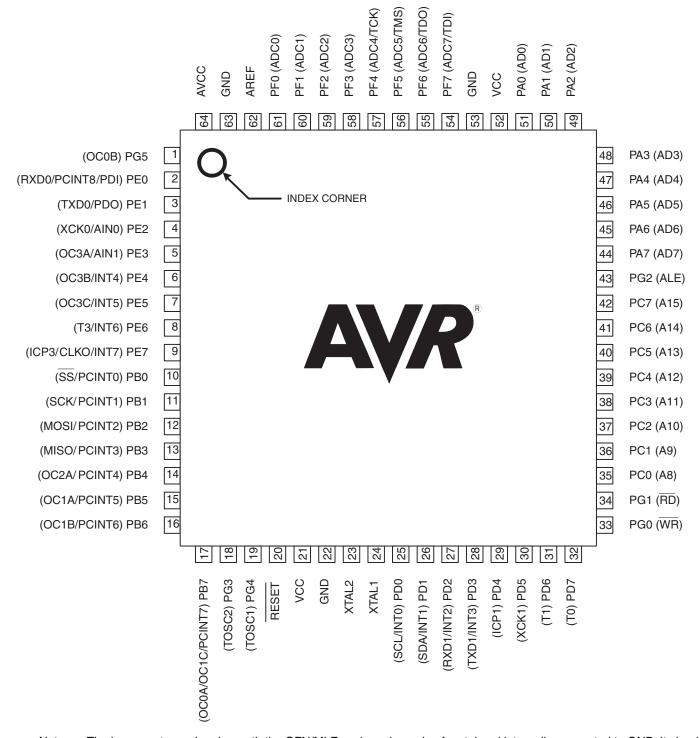
Table 1-1. CBGA-pinout ATmega640/1280/2560

	1	2	3	4	5	6	7	8	9	10
	'	2	3	4	3	0	1	0	9	10
Α	GND	AREF	PF0	PF2	PF5	PK0	PK3	PK6	GND	VCC
В	AVCC	PG5	PF1	PF3	PF6	PK1	PK4	PK7	PA0	PA2
С	PE2	PE0	PE1	PF4	PF7	PK2	PK5	PJ7	PA1	PA3
D	PE3	PE4	PE5	PE6	PH2	PA4	PA5	PA6	PA7	PG2
E	PE7	PH0	PH1	PH3	PH5	PJ6	PJ5	PJ4	PJ3	PJ2
F	VCC	PH4	PH6	PB0	PL4	PD1	PJ1	PJ0	PC7	GND
G	GND	PB1	PB2	PB5	PL2	PD0	PD5	PC5	PC6	VCC
Н	PB3	PB4	RESET	PL1	PL3	PL7	PD4	PC4	PC3	PC2
J	PH7	PG3	PB6	PL0	XTAL2	PL6	PD3	PC1	PC0	PG1
K	PB7	PG4	VCC	GND	XTAL1	PL5	PD2	PD6	PD7	PG0

Note: The functions for each pin is the same as for the 100 pin packages shown in Figure 1-1 on page 2.



Figure 1-3. Pinout ATmega1281/2561



Note: The large center pad underneath the QFN/MLF package is made of metal and internally connected to GND. It should be soldered or glued to the board to ensure good mechanical stability. If the center pad is left unconnected, the package might loosen from the board.

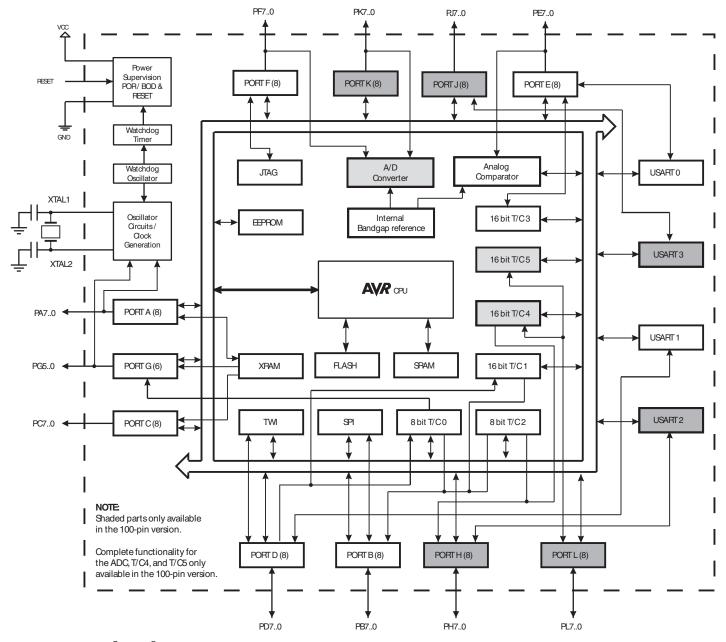


2. Overview

The ATmega640/1280/1281/2560/2561 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega640/1280/1281/2560/2561 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

2.1 Block Diagram

Figure 2-1. Block Diagram



The Atmel® AVR® core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.



The ATmega640/1280/1281/2560/2561 provides the following features: 64K/128K/256K bytes of In-System Programmable Flash with Read-While-Write capabilities, 4Kbytes EEPROM, 8Kbytes SRAM, 54/86 general purpose I/O lines, 32 general purpose working registers, Real Time Counter (RTC), six flexible Timer/Counters with compare modes and PWM, four USARTs, a byte oriented 2-wire Serial Interface, a 16-channel, 10-bit ADC with optional differential input stage with programmable gain, programmable Watchdog Timer with Internal Oscillator, an SPI serial port, IEEE® std. 1149.1 compliant JTAG test interface, also used for accessing the On-chip Debug system and programming and six software selectable power saving modes. The Idle mode stops the CPU while allowing the SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next interrupt or Hardware Reset. In Power-save mode, the asynchronous timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the Crystal/Resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

Atmel offers the QTouch[®] library for embedding capacitive touch buttons, sliders and wheels functionality into AVR microcontrollers. The patented charge-transfer signal acquisition offersrobust sensing and includes fully debounced reporting of touch keys and includes Adjacent Key Suppression[®] (AKS[®]) technology for unambiguous detection of key events. The easy-to-use QTouch Suite toolchain allows you to explore, develop and debug your own touch applications.

The device is manufactured using the Atmel high-density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega640/1280/1281/2560/2561 is a powerful microcontroller that provides a highly flexible and cost effective solution to many embedded control applications.

The ATmega640/1280/1281/2560/2561 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.



2.3.6 Port D (PD7..PD0)

Port D is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port D output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port D also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 80.

2.3.7 Port E (PE7..PE0)

Port E is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port E output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port E pins that are externally pulled low will source current if the pull-up resistors are activated. The Port E pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port E also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 82.

2.3.8 Port F (PF7..PF0)

Port F serves as analog inputs to the A/D Converter.

Port F also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port F output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port F pins that are externally pulled low will source current if the pull-up resistors are activated. The Port F pins are tri-stated when a reset condition becomes active, even if the clock is not running. If the JTAG interface is enabled, the pull-up resistors on pins PF7(TDI), PF5(TMS), and PF4(TCK) will be activated even if a reset occurs.

Port F also serves the functions of the JTAG interface.

2.3.9 Port G (PG5..PG0)

Port G is a 6-bit I/O port with internal pull-up resistors (selected for each bit). The Port G output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port G pins that are externally pulled low will source current if the pull-up resistors are activated. The Port G pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port G also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 86.

2.3.10 Port H (PH7..PH0)

Port H is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port H output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port H pins that are externally pulled low will source current if the pull-up resistors are activated. The Port H pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port H also serves the functions of various special features of the ATmega640/1280/2560 as listed on page 88.

2.3.11 Port J (PJ7..PJ0)

Port J is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port J output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port J pins that are externally pulled low will source current if the pull-up resistors are activated. The Port J pins are tri-stated when a reset condition becomes active, even if the clock is not running. Port J also serves the functions of various special features of the ATmega640/1280/2560 as listed on page 90.



3. Resources

A comprehensive set of development tools and application notes, and datasheets are available for download on http://www.atmel.com/avr.

4. About Code Examples

This documentation contains simple code examples that briefly show how to use various parts of the device. Be aware that not all C compiler vendors include bit definitions in the header files and interrupt handling in C is compiler dependent. Confirm with the C compiler documentation for more details.

These code examples assume that the part specific header file is included before compilation. For I/O registers located in extended I/O map, "IN", "OUT", "SBIS", "SBIC", "CBI", and "SBI" instructions must be replaced with instructions that allow access to extended I/O. Typically "LDS" and "STS" combined with "SBRS", "SBRC", "SBR", and "CBR".

5. Data Retention

Reliability Qualification results show that the projected data retention failure rate is much less than 1 ppm over 20 years at 85°C or 100 years at 25°C.

6. Capacitive touch sensing

The Atmel[®] QTouch[®] Library provides a simple to use solution to realize touch sensitive interfaces on most Atmel AVR[®] microcontrollers. The QTouch Library includes support for the QTouch and QMatrix acquisition methods.

Touch sensing can be added to any application by linking the appropriate Atmel QTouch Library for the AVR Microcontroller. This is done by using a simple set of APIs to define the touch channels and sensors, and then calling the touch sensing API's to retrieve the channel information and determine the touch sensor states.

The QTouch Library is FREE and downloadable from the Atmel website at the following location: www.atmel.com/qtouchlibrary. For implementation details and other information, refer to the Atmel QTouch Library User Guide - also available for download from the Atmel website.



7. Register Summary

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0x1FF)	Reserved	-	-	-	-	-	-	-	-	
	Reserved	-	-	-	-	-	-	-	-	
(0x13F)	Reserved									
(0x13E)	Reserved									
(0x13D)	Reserved									
(0x13C)	Reserved									
(0x13B)	Reserved									
(0x13A)	Reserved									
(0x139)	Reserved									
(0x138)	Reserved									
(0x137)	Reserved UDR3				LICADTO I/O	Data Danistan				nama 010
(0x136) (0x135)	UBRR3H	-	-	-	USANTS I/C	Data Register	ICADT2 Paud Pa	te Register High E	Duto	page 218
(0x135) (0x134)	UBRR3L	-	-			ate Register Low I		te Register High E	byte	page 222 page 222
(0x134)	Reserved	-	-	-	- L		-	-	-	page 222
(0x132)	UCSR3C	UMSEL31	UMSEL30	UPM31	UPM30	USBS3	UCSZ31	UCSZ30	UCPOL3	page 235
(0x131)	UCSR3B	RXCIE3	TXCIE3	UDRIE3	RXEN3	TXEN3	UCSZ32	RXB83	TXB83	page 234
(0x130)	UCSR3A	RXC3	TXC3	UDRE3	FE3	DOR3	UPE3	U2X3	MPCM3	page 233
(0x12F)	Reserved	-	-	-	-	-	-	-	-	P 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
(0x12E)	Reserved	-	-	-	-	-	-	-	-	
(0x12D)	OCR5CH			Timer/Co	unter5 - Output C	ompare Register	C High Byte			page 160
(0x12C)	OCR5CL					Compare Register				page 160
(0x12B)	OCR5BH			Timer/Co	unter5 - Output C	ompare Register	B High Byte			page 160
(0x12A)	OCR5BL					Compare Register				page 160
(0x129)	OCR5AH			Timer/Co	unter5 - Output C	ompare Register	A High Byte			page 160
(0x128)	OCR5AL			Timer/Co	unter5 - Output C	ompare Register	A Low Byte			page 160
(0x127)	ICR5H			Timer/0	Counter5 - Input (Capture Register	High Byte			page 161
(0x126)	ICR5L			Timer/	Counter5 - Input	Capture Register	Low Byte			page 161
(0x125)	TCNT5H			Time	er/Counter5 - Co	unter Register Hig	gh Byte			page 158
(0x124)	TCNT5L			Tim	er/Counter5 - Co	unter Register Lo	w Byte			page 158
(0x123)	Reserved	-	-	-	-	-	-	-	-	
(0x122)	TCCR5C	FOC5A	FOC5B	FOC5C	-	-	-	-	-	page 157
(0x121)	TCCR5B	ICNC5	ICES5	-	WGM53	WGM52	CS52	CS51	CS50	page 156
(0x120)	TCCR5A	COM5A1	COM5A0	COM5B1	COM5B0	COM5C1	COM5C0	WGM51	WGM50	page 154
(0x11F)	Reserved	-	-	-	-	-	-	-	-	
(0x11E)	Reserved	-	-	-	-	-	-	-	-	
(0x11D)	Reserved Reserved	-	-	-	-	-	-	-	-	
(0x11C) (0x11B)	Reserved	-	-	-	-	-	-	-	-	
(0x11B) (0x11A)	Reserved	-	-		-	-	-	_	-	
(0x11A)	Reserved	-	-	-	-	-	-	-	-	
(0x118)	Reserved	-	-	-	-	-	-	-	-	
(0x117)	Reserved	-	_	-	-	_	_	-	-	
(0x116)	Reserved	-	-	-	-	-	-	-	-	
(0x115)	Reserved	-	-	-	-	-	-	-	-	
(0x114)	Reserved	-	-	-	-	-	-	-	-	
(0x113)	Reserved	-	-	-	-	-	-	-	-	
(0x112)	Reserved	-	-	-	-	-	-	-	-	
(0x111)	Reserved	-	-	-	-	-	-	-	-	
(0x110)	Reserved	-	-	-	-	-	-	-	-	
(0x10F)	Reserved	-	-	-	-	-	-	-	-	
(0x10E)	Reserved	-	-	-	-	-	-	-	-	
(0x10D)	Reserved	-	-	-	-	-	-	-	-	
(0x10C)	Reserved	-	-	-	-	-	-	-	- DODTI O	
(0x10B)	PORTL	PORTL7	PORTL6	PORTL5	PORTL4	PORTL3	PORTL2	PORTL1	PORTL0	page 100
(0x10A)	DDRL PINL	DDL7 PINL7	DDL6 PINL6	DDL5	DDL4	DDL3	DDL2	DDL1	DDL0	page 100
(0x109)	PORTK	PINL7 PORTK7	PORTK6	PINL5 PORTK5	PINL4 PORTK4	PINL3 PORTK3	PINL2 PORTK2	PINL1 PORTK1	PINL0 PORTK0	page 100
(0x108)	DDRK	DDK7	DDK6	DDK5	DDK4	DDK3	DDK2	DDK1	DDK0	page 99 page 99
(0v107)		אטט			PINK4	PINK3	PINK2	PINK1	PINK0	page 99
(0x107) (0x106)		PINK7	PINKE			I HALLO	1 1131134	1 11313.1	I II VI VU	page 00
(0x106)	PINK	PINK7 PORT.I7	PINK6 PORTJ6	PINK5 PORTJ5			PURT 12	PORT I1	PORT.In	page 90
(0x106) (0x105)	PINK PORTJ	PORTJ7	PORTJ6	PORTJ5	PORTJ4	PORTJ3	PORTJ2 DDJ2	PORTJ1	PORTJ0	page 99
(0x106) (0x105) (0x104)	PINK PORTJ DDRJ	PORTJ7 DDJ7	PORTJ6 DDJ6	PORTJ5 DDJ5	PORTJ4 DDJ4	PORTJ3 DDJ3	DDJ2	DDJ1	DDJ0	page 99
(0x106) (0x105)	PINK PORTJ	PORTJ7	PORTJ6	PORTJ5	PORTJ4	PORTJ3				



Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0x100)	PINH	PINH7	PINH6	PINH5	PINH4	PINH3	PINH2	PINH1	PINH0	page 99
(0xFF)	Reserved	-	-	-	-	-	-	-	-	
(0xFE)	Reserved	-	-	-	-	-	-	-	-	
(0xFD)	Reserved	-	-	-	-	-	-	-	-	
(0xFC)	Reserved	-	-	-	-	-	-	-	-	
(0xFB)	Reserved	-	-	-	-	-	-	-	-	
(0xFA)	Reserved	-	-	-	-	-	-	-	-	
(0xF9)	Reserved	-	-	-	-	-	-	-	-	
(0xF8)	Reserved	-	-	-	-	-	-	-	-	
(0xF7) (0xF6)	Reserved Reserved	-	-	-	-	-	-	-	-	
(0xF5)	Reserved	-	-	-	-	-	-	-	-	
(0xF4)	Reserved	_	_	-	_	_	_	-	_	
(0xF3)	Reserved	-	-	-	-	_	-	-	-	
(0xF2)	Reserved	-	-	-	-	-	-	-	-	
(0xF1)	Reserved	-	-	-	-	-	-	-	-	
(0xF0)	Reserved	-	-	-	-	-	-	-	-	
(0xEF)	Reserved	-	-	-	-	-	-	-	-	
(0xEE)	Reserved	-	-	-	-	-	-	-	-	
(0xED)	Reserved	-	-	-	-	-	-	-	-	
(0xEC)	Reserved	-	-	-	-	-	-	-	-	
(0xEB)	Reserved	-	-	-	-		-	-	-	
(0xEA)	Reserved	-	-	-	-	-	-	-	-	
(0xE9)	Reserved	-	-	-	-	-	-	-	-	
(0xE8)	Reserved	-	-	-	-	-	-	-	-	
(0xE7)	Reserved	-	-	-	-		-	-	-	
(0xE6)	Reserved	-	-	-	-	-	-	-	-	
(0xE5) (0xE4)	Reserved Reserved	-	-	-	-	-	-	-	-	
(0xE3)	Reserved	-	-	-	-	-	-	-	-	
(0xE2)	Reserved	-	-	-	-	_	-	-	-	
(0xE1)	Reserved	-	-	-	-		-	-	-	
(0xE0)	Reserved	-	-	-	-		-	-	-	
(0xDF)	Reserved	-	-	-	-	-	-	-	-	
(0xDE)	Reserved	-	-	-	-	-	-	-	-	
(0xDD)	Reserved	-	-	-	-		-	-	-	
(0xDC)	Reserved	-	-	-	-	-	-	-	-	
(0xDB)	Reserved	-	-	-	-	-	-	-	-	
(0xDA)	Reserved	-	-	-	-	-	-	-	-	
(0xD9)	Reserved	-	-	-	-		-	-	-	
(0xD8)	Reserved	-	-	-	-	-	-	-	-	
(0xD7)	Reserved	-	-	-	LICADTO I//	Dota Parietar	-	-	-	2000 010
(0xD6) (0xD5)	UDR2 UBRR2H	-	-	-	USART2 I/C	Data Register	JSART2 Baud Rat	o Posistor High F	Duto	page 218 page 222
(0xD4)	UBRR2L	-	-			ate Register Low I		e negister nigit t	byte	page 222
(0xD3)	Reserved	-	-	-	-	-	-	-	-	page 222
(0xD3)	UCSR2C	UMSEL21	UMSEL20	UPM21	UPM20	USBS2	UCSZ21	UCSZ20	UCPOL2	page 235
(0xD1)	UCSR2B	RXCIE2	TXCIE2	UDRIE2	RXEN2	TXEN2	UCSZ22	RXB82	TXB82	page 234
(0xD0)	UCSR2A	RXC2	TXC2	UDRE2	FE2	DOR2	UPE2	U2X2	MPCM2	page 233
(0xCF)	Reserved	-	-	-	-	-	-	-	-	
(0xCE)	UDR1				USART1 I/C	Data Register				page 218
(0xCD)	UBRR1H	-	-	-	-	U	JSART1 Baud Rat	e Register High E	Byte	page 222
(0xCC)	UBRR1L					ate Register Low I				page 222
(0xCB)	Reserved	-	-	-	-	-	-	-	-	
(0xCA)	UCSR1C	UMSEL11	UMSEL10	UPM11	UPM10	USBS1	UCSZ11	UCSZ10	UCPOL1	page 235
(0xC9)	UCSR1B	RXCIE1	TXCIE1	UDRIE1	RXEN1	TXEN1	UCSZ12	RXB81	TXB81	page 234
(0xC8)	UCSR1A	RXC1	TXC1	UDRE1	FE1	DOR1	UPE1	U2X1	MPCM1	page 233
(0xC7)	Reserved UDR0	-	-	-	- LICADTO I/C	Doto Basista	-	-	-	noge 010
(0xC6) (0xC5)	UBRR0H	-	-	-	USARTO I/C	Data Register	JSART0 Baud Rat	a Register High	Syte	page 218 page 222
(0xC4)	UBRR0L	_				ate Register Low I		o riogisioi Migil E	.y.0	page 222
(0xC4) (0xC3)	Reserved	-	-	-				-	-	paye 222
(0xC2)	UCSR0C	UMSEL01	UMSEL00	UPM01	UPM00	USBS0	UCSZ01	UCSZ00	UCPOL0	page 235
(0xC1)	UCSR0B	RXCIE0	TXCIE0	UDRIE0	RXEN0	TXEN0	UCSZ02	RXB80	TXB80	page 234
(0xC0)	UCSR0A	RXC0	TXC0	UDRE0	FE0	DOR0	UPE0	U2X0	MPCM0	page 234
(0xBF)	Reserved	-	-	-	-	-	-	-	-	
	Reserved	-	-	-	-	-	-	-	-	
(0xBE)	neserveu									



Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0x78)	ADCL				ADC Data Re	egister Low byte		•		page 286
(0x77)	Reserved	-	-	-	-	-	-	-	-	
(0x76)	Reserved	-	-	-	-	-	-	-	-	
(0x75)	XMCRB	XMBK	-	-	-	-	XMM2	XMM1	XMM0	page 38
(0x74) (0x73)	XMCRA TIMSK5	SRE -	SRL2	SRL1 ICIE5	SRL0	SRW11 OCIE5C	SRW10 OCIE5B	SRW01 OCIE5A	SRW00 TOIE5	page 36
(0x73) (0x72)	TIMSK4	-	-	ICIE5	-	OCIE4C	OCIE3B OCIE4B	OCIE4A	TOIE3	page 162 page 161
(0x71)	TIMSK3	-	-	ICIE3	-	OCIE3C	OCIE3B	OCIE3A	TOIE3	page 161
(0x70)	TIMSK2	-	-	-	-	-	OCIE2B	OCIE2A	TOIE2	page 188
(0x6F)	TIMSK1	-	-	ICIE1	-	OCIE1C	OCIE1B	OCIE1A	TOIE1	page 161
(0x6E)	TIMSK0	-	-	-	-	-	OCIE0B	OCIE0A	TOIE0	page 131
(0x6D)	PCMSK2	PCINT23	PCINT22	PCINT21	PCINT20	PCINT19	PCINT18	PCINT17	PCINT16	page 113
(0x6C)	PCMSK1	PCINT15	PCINT14	PCINT13	PCINT12	PCINT11	PCINT10	PCINT9	PCINT8	page 113
(0x6B)	PCMSK0	PCINT7	PCINT6	PCINT5	PCINT4	PCINT3	PCINT2	PCINT1	PCINT0	page 114
(0x6A) (0x69)	EICRB EICRA	ISC71 ISC31	ISC70 ISC30	ISC61 ISC21	ISC60 ISC20	ISC51 ISC11	ISC50 ISC10	ISC41 ISC01	ISC40 ISC00	page 110
(0x69) (0x68)	PCICR	-	-	-	15020	-	PCIE2	PCIE1	PCIE0	page 110 page 112
(0x67)	Reserved	-	-	-	-	-	-	-	-	page 112
(0x66)	OSCCAL				Oscillator Cal	bration Register				page 48
(0x65)	PRR1	-	-	PRTIM5	PRTIM4	PRTIM3	PRUSART3	PRUSART2	PRUSART1	page 56
(0x64)	PRR0	PRTWI	PRTIM2	PRTIM0	-	PRTIM1	PRSPI	PRUSART0	PRADC	page 55
(0x63)	Reserved	-	-	-	-	-	-	-	-	
(0x62)	Reserved	-	-	-	-	-	-	-	-	
(0x61)	CLKPR	CLKPCE	-	-	-	CLKPS3	CLKPS2	CLKPS1	CLKPS0	page 48
(0x60)	WDTCSR	WDIF	WDIE	WDP3	WDCE	WDE V	WDP2	WDP1	WDP0	page 65
0x3F (0x5F) 0x3E (0x5E)	SREG SPH	SP15	T SP14	H SP13	S SP12	SP11	N SP10	Z SP9	C SP8	page 13 page 15
0x3D (0x5D)	SPL	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0	page 15
0x3C (0x5C)	EIND	-	-	-	-	-	-	-	EIND0	page 16
0x3B (0x5B)	RAMPZ	-	-	-	-	-	-	RAMPZ1	RAMPZ0	page 16
0x3A (0x5A)	Reserved	-	-	-	-	-	-	-	-	
0x39 (0x59)	Reserved	-	-	-	-	-	-	-	-	
0x38 (0x58)	Reserved	-	-	-	-	-	-	-	-	
0x37 (0x57)	SPMCSR	SPMIE	RWWSB	SIGRD	RWWSRE	BLBSET	PGWRT	PGERS	SPMEN	page 323
0x36 (0x56)	Reserved	- ITD	-	-	- DUD	-	-	- IVCEI	-	name C4 100 00 001
0x35 (0x55) 0x34 (0x54)	MCUCR MCUSR	JTD -	-	-	PUD JTRF	WDRF	BORF	IVSEL EXTRF	IVCE PORF	page 64, 108, 96, 301 page 301
0x33 (0x53)	SMCR	-	-	-	-	SM2	SM1	SM0	SE	page 50
0x32 (0x52)	Reserved	-	-	-	-	-	-	-	-	page
0x31 (0x51)	OCDR	OCDR7	OCDR6	OCDR5	OCDR4	OCDR3	OCDR2	OCDR1	OCDR0	page 294
0x30 (0x50)	ACSR	ACD	ACBG	ACO	ACI	ACIE	ACIC	ACIS1	ACIS0	page 266
0x2F (0x4F)	Reserved	-	-	-	-	-	-	-	-	
0x2E (0x4E)	SPDR				SPI Da	ta Register	1	ı		page 199
0x2D (0x4D)	SPSR	SPIF	WCOL	-	-	-	-	-	SPI2X	page 198
0x2C (0x4C)	SPCR	SPIE	SPE	DORD	MSTR Conoral Burns	CPOL	CPHA	SPR1	SPR0	page 197
0x2B (0x4B) 0x2A (0x4A)	GPIOR2 GPIOR1					se I/O Register 2 se I/O Register 1				page 36 page 36
0x29 (0x49)	Reserved	-	-	-	-	-	-	-	-	page oo
0x28 (0x48)	OCR0B			Tin	ner/Counter0 Out	out Compare Reg	ister B			page 130
0x27 (0x47)	OCR0A				ner/Counter0 Out					page 130
0x26 (0x46)	TCNT0				Timer/Co	unter0 (8 Bit)				page 130
0x25 (0x45)	TCCR0B	FOC0A	FOC0B	-	-	WGM02	CS02	CS01	CS00	page 129
0x24 (0x44)	TCCR0A	COM0A1	COM0A0	COM0B1	COM0B0	-	-	WGM01	WGM00	page 126
0x23 (0x43)	GTCCR	TSM	•	-	-	-	-	PSRASY	PSRSYNC	page 166, 189
0x22 (0x42) 0x21 (0x41)	EEARH EEARL	-	-	-	EEPROM Addres		EEPROM Address	s Hegister High B	уте	page 34 page 34
0x21 (0x41) 0x20 (0x40)	EEDR					s недізіег Low в Data Register	yıe			page 34
0x1F (0x3F)	EECR	-	-	EEPM1	EEPM0	EERIE	EEMPE	EEPE	EERE	page 34
0x1E (0x3E)	GPIOR0					se I/O Register 0				page 36
0x1D (0x3D)	EIMSK	INT7	INT6	INT5	INT4	INT3	INT2	INT1	INT0	page 111
0x1C (0x3C)	EIFR	INTF7	INTF6	INTF5	INTF4	INTF3	INTF2	INTF1	INTF0	page 112
0x1B (0x3B)	PCIFR	-	-	-	-		PCIF2	PCIF1	PCIF0	page 113
0x1A (0x3A)	TIFR5	-	-	ICF5	-	OCF5C	OCF5B	OCF5A	TOV5	page 162
0x19 (0x39)	TIFR4	-	-	ICF4	-	OCF4C	OCF4B	OCF4A	TOV4	page 162
0x18 (0x38)	TIFR3	-	-	ICF3	-	OCF3C	OCF3B	OCF3A	TOV3	page 162
0x17 (0x37) 0x16 (0x36)	TIFR2 TIFR1	-	-	- ICF1	-	OCF1C	OCF2B OCF1B	OCF2A OCF1A	TOV2 TOV1	page 188
0x16 (0x36) 0x15 (0x35)	TIFRI TIFR0	-	-	-	-	-	OCF1B OCF0B	OCF1A OCF0A	TOV1	page 162 page 131
0.10 (0.00)	III NO	_	-	-	_	-	1 00100	COLON	1000	page 101



Mnemonics	Operands	Description	Operation	Flags	#Clocks
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
MCU CONTROL INS	TRUCTIONS				
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

EICALL and EIJMP do not exist in ATmega640/1280/1281. ELPM does not exist in ATmega640. Note:



Ordering Information 9.

9.1 ATmega640

Speed [MHz] ⁽²⁾	Power Supply	Ordering Code	Package ⁽¹⁾⁽³⁾	Operation Range
8	1.8 - 5.5V	ATmega640V-8AU ATmega640V-8AUR ⁽⁴⁾ ATmega640V-8CU ATmega640V-8CUR ⁽⁴⁾	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega640-16AU ATmega640-16AUR ⁽⁴⁾ ATmega640-16CU ATmega640-16CUR ⁽⁴⁾	100A 100A 100C1 100C1	industrial (*40 0 to 65 0)

- Notes: 1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
 - 2. See "Speed Grades" on page 357.
 - 3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
 - 4. Tape & Reel.

	Package Type
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)



ATmega1281 9.3

Speed [MHz] ⁽²⁾	Power Supply	Ordering Code	Package ⁽¹⁾⁽³⁾	Operation Range
8	1.8 - 5.5V	ATmega1281V-8AU ATmega1281V-8AUR ⁽⁴⁾ ATmega1281V-8MU ATmega1281V-8MUR ⁽⁴⁾	64A 64A 64M2 64M2	Industrial
16	2.7 - 5.5V	ATmega1281-16AU ATmega1281-16AUR ⁽⁴⁾ ATmega1281-16MU ATmega1281-16MUR ⁽⁴⁾	64A 64A 64M2 64M2	(-40°C to 85°C)

- Notes: 1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
 - 2. See "Speed Grades" on page 357.
 - 3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
 - 4. Tape & Reel.

	Package Type
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)



9.4 ATmega2560

Speed [MHz] ⁽²⁾	Power Supply	Ordering Code	Package ⁽¹⁾⁽³⁾	Operation Range
8	1.8V - 5.5V	ATmega2560V-8AU ATmega2560V-8AUR ⁽⁴⁾ ATmega2560V-8CU ATmega2560V-8CUR ⁽⁴⁾	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	4.5V - 5.5V	ATmega2560-16AU ATmega2560-16AUR ⁽⁴⁾ ATmega2560-16CU ATmega2560-16CUR ⁽⁴⁾	100A 100A 100C1 100C1	industrial (-40 0 to 65 0)

Notes: 1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.

- 2. See "Speed Grades" on page 357.
- 3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
- 4. Tape & Reel.

	Package Type
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)



9.5 ATmega2561

Speed [MHz] ⁽²⁾	Power Supply	Ordering Code	Package ⁽¹⁾⁽³⁾	Operation Range	
8	1.8V - 5.5V	ATmega2561V-8AU ATmega2561V-8AUR ⁽⁴⁾ ATmega2561V-8MU ATmega2561V-8MUR ⁽⁴⁾	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)	
16	4.5V - 5.5V	ATmega2561-16AU ATmega2561-16AUR ⁽⁴⁾ ATmega2561-16MU ATmega2561-16MUR ⁽⁴⁾	64A 64A 64M2 64M2		

Notes: 1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.

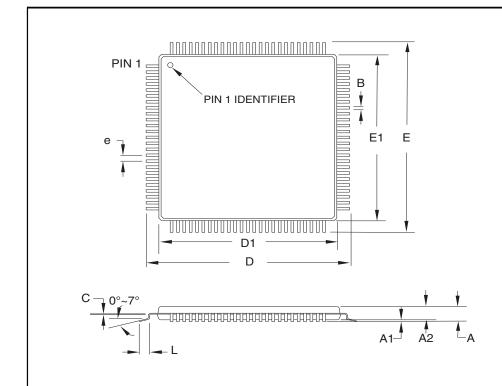
- 2. See "Speed Grades" on page 357.
- 3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
- 4. Tape & Reel.

Package Type		
64 A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)	
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)	



10. Packaging Information

10.1 100A



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	_	_	1.20	
A1	0.05	_	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
Е	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
В	0.17	_	0.27	
С	0.09	_	0.20	
L	0.45	_	0.75	
е		0.50 TYP		

Notes:

- 1. This package conforms to JEDEC reference MS-026, Variation AED.
- Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
- 3. Lead coplanarity is 0.08 mm maximum.

2010-10-20

	TITLE	DRAWING NO.	REV.
Atmel Package Drawing Contact: packagedrawings@atmel.com	100A , 100-lead, 14 x 14 mm Body Size, 1.0 mm Body Thickness, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	100A	D



11. Errata

11.1 ATmega640 rev. B

- Inaccurate ADC conversion in differential mode with 200x gain
- · High current consumption in sleep mode

1. Inaccurate ADC conversion in differential mode with 200x gain

With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

Problem Fix/Workaround

None.

2. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem Fix/Workaround

Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.2 ATmega640 rev. A

- Inaccurate ADC conversion in differential mode with 200x gain
- High current consumption in sleep mode

1. Inaccurate ADC conversion in differential mode with 200x gain

With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

Problem Fix/Workaround

None.

2. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem Fix/Workaround

Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.3 ATmega1280 rev. B

· High current consumption in sleep mode

1. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem Fix/Workaround

Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.4 ATmega1280 rev. A

- Inaccurate ADC conversion in differential mode with 200x gain
- High current consumption in sleep mode

1. Inaccurate ADC conversion in differential mode with 200x gain

With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.



11.10 ATmega2560 rev. C

· High current consumption in sleep mode

1. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem Fix/Workaround

Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.11 ATmega2560 rev. B

Not sampled.

11.12 ATmega2560 rev. A

- Non-Read-While-Write area of flash not functional
- · Part does not work under 2.4 volts
- Incorrect ADC reading in differential mode
- Internal ADC reference has too low value
- . IN/OUT instructions may be executed twice when Stack is in external RAM
- EEPROM read from application code does not work in Lock Bit Mode 3

1. Non-Read-While-Write area of flash not functional

The Non-Read-While-Write area of the flash is not working as expected. The problem is related to the speed of the part when reading the flash of this area.

Problem Fix/Workaround

- Only use the first 248K of the flash.
- If boot functionality is needed, run the code in the Non-Read-While-Write area at maximum 1/4th of the maximum frequency of the device at any given voltage. This is done by writing the CLKPR register before entering the boot section of the code.

2. Part does not work under 2.4 volts

The part does not execute code correctly below 2.4 volts.

Problem Fix/Workaround

Do not use the part at voltages below 2.4 volts.

3. Incorrect ADC reading in differential mode

The ADC has high noise in differential mode. It can give up to 7 LSB error.

Problem Fix/Workaround

Use only the 7 MSB of the result when using the ADC in differential mode.

4. Internal ADC reference has too low value

The internal ADC reference has a value lower than specified.

Problem Fix/Workaround

- Use AVCC or external reference.
- The actual value of the reference can be measured by applying a known voltage to the ADC when using the internal reference. The result when doing later conversions can then be calibrated.



5. IN/OUT instructions may be executed twice when Stack is in external RAM

If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

- If reading SREG it will appear that the I-flag is cleared.
- If writing to the PIN registers, the port will toggle twice.
- If reading registers with interrupt flags, the flags will appear to be cleared.

Problem Fix/Workaround

There are two application workarounds, where selecting one of them, will be omitting the issue:

- Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.
- Use internal RAM for stack pointer.

6. EEPROM read from application code does not work in Lock Bit Mode 3

When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

Problem Fix/Workaround

Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

11.13 ATmega2561 rev. F

- ADC differential input amplification by 46dB (200x) not functional
- ADC differential input amplification by 46dB (200x) not functional Problem Fix/Workaround

None.

11.14 ATmega2561 rev. E

No known errata.

11.15 ATmega2561 rev. D

Not sampled.

11.16 ATmega2561 rev. C

· High current consumption in sleep mode.

1. High current consumption in sleep mode

If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

Problem Fix/Workaround

Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.17 ATmega2561 rev. B

Not sampled.



11.18 ATmega2561 rev. A

- Non-Read-While-Write area of flash not functional
- · Part does not work under 2.4 Volts
- Incorrect ADC reading in differential mode
- Internal ADC reference has too low value
- IN/OUT instructions may be executed twice when Stack is in external RAM
- EEPROM read from application code does not work in Lock Bit Mode 3

1. Non-Read-While-Write area of flash not functional

The Non-Read-While-Write area of the flash is not working as expected. The problem is related to the speed of the part when reading the flash of this area.

Problem Fix/Workaround

- Only use the first 248K of the flash.
- If boot functionality is needed, run the code in the Non-Read-While-Write area at maximum 1/4th of the maximum frequency of the device at any given voltage. This is done by writing the CLKPR register before entering the boot section of the code.

2. Part does not work under 2.4 volts

The part does not execute code correctly below 2.4 volts.

Problem Fix/Workaround

Do not use the part at voltages below 2.4 volts.

3. Incorrect ADC reading in differential mode

The ADC has high noise in differential mode. It can give up to 7 LSB error.

Problem Fix/Workaround

Use only the 7 MSB of the result when using the ADC in differential mode.

4. Internal ADC reference has too low value

The internal ADC reference has a value lower than specified.

Problem Fix/Workaround

- Use AVCC or external reference.
- The actual value of the reference can be measured by applying a known voltage to the ADC when using the internal reference. The result when doing later conversions can then be calibrated.

5. IN/OUT instructions may be executed twice when Stack is in external RAM

If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

- If reading SREG it will appear that the I-flag is cleared.
- If writing to the PIN registers, the port will toggle twice.
- If reading registers with interrupt flags, the flags will appear to be cleared.

Problem Fix/Workaround

There are two application workarounds, where selecting one of them, will be omitting the issue:

- Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.

